L Number 1	Hits 1	Search Text "20020190255"	DB USPAT: US-PGPUB;	Time stamp 2003/03/12 16:59
			EPO; JPO; DERWENT; IBM_TDB	
2	335424	fujitsu.AS.	USPAT; US-PGPUB; EPO; JPO;	2003/03/12 17:00
3	21228	PMOS and NMOS	DFRWENT; IBM_TDB USPAT; US-PGPUB;	2003/03/12 17:00
4	85801	CMOS	EPO: JPO; DERWENT; IBM_TDB USPAT;	2003/03/12 17:01
·	03001		US-PGPUB; EPO, JPO; DERWENT;	2003/03/12 17.01
5	6393	Kitahara.INV.	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/03/12 17:01
6	233	fujitsu.AS. and Kitahara.INV.	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/03/12 17:02
7	3	(fujitsu.AS. and Kitahara.INV.) and CMOS	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/03/12 17:04
8	50	(fujitsu.AS. and Kitahara.INV.) and memory	EPO: JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/03/12 17:09
9	1	CMOS adj IC adj layout	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/03/12 17:11
10	11169	CMOS and layout	EPO: JPO: DERWENT: IBM_TDB USPAT:	2002/02/12 17.11
10	11107	Cirion and layout	US-PGPUB; EPO; JPO; DERWENT;	2003/03/12 17:11
11	191	CMOS near layout	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003 03 12 17:12
12	2425	CMOS same layout	DERWENT: IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 17:13

USPAT: 2003 03 12 17:13 US-PGPUB:

EPO; JPO; DERWENT; IBM\_TDB

L Number	Hits 1	Search Text "20020190255"	DB USPAT; US-PGPUB;	Time stamp 2003/03/12 16:59
2	335424	fujitsu.AS.	EPO; JPO; DERWENT; IBM_TDB USPAT.	2003/03/12 17:00
			US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	
3	21228	PMOS and NMOS	USPAT. US-PGPUB: EPO; JPO; DERWENT;	2003 03/12 17:00
4	85801	CMOS	IBM_TDB USPAT: US-PGPUB; EPO; JPO;	2003/03/12 17:01
5	6393	Kitahara.INV.	DERWENT: IBM_TDB USPAT: US-PGPUB:	2003/03/12 17:01
6	233	fujitsu.AS. and Kitahara.INV.	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/03/12 17:02
7	3	(fujitsu.AS. and Kitahara.INV.) and CMOS	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003 03 12 17:04
8	50	(fujitsu.AS. and Kitahara.INV.) and memory	EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/03/12 17:09
9	1	CMOS adj IC adj layout	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2003/03/12 17:11
10	11169	CMOS and layout	DERWENT; IBM_TDB USPAT; US-PGPUB;	2003/03/12 17:11
11	191	CMOS near layout	EPO, JPO; DERWENT; IBM_TDB USPAT; US-PGPUB;	2003-03-12-17:12
12	2425	CMOS same layout	EPO. JPO: DERWENT: IBM_TDB USPAT: US-PGPUB: EPO: JPO: DERWENT:	2003/03/12 17:13
			IBM_TDB	

64 (CMOS near layout) and wiring

USPAT; US-PGPUB; 2003/03/12 17:13

EPO; JPO; DERWENT; IBM\_TDB